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PATENT

Docket No. JCLA7022

Date: 10-22-2001

Page 1

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231
ATTENTION: APPLICATION BRANCH

Sir:

Transmitted herewith for filing is the patent application of

Inventors: Ko-Yan Shih; Ming-Hsun Hsu

For: METHOD AND CIRCUIT FOR TESTING A CHIP

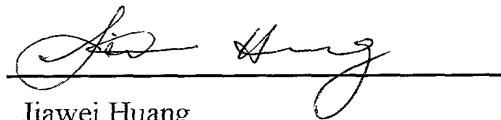
Enclosed are:

- Specification 14 pages.
- 4 Sheets of drawings
- Recordation Form Cover sheet with 2 pages assignment.
- A certified copy of Taiwan Patent Application No. dated
- SIGNED** declaration and power of attorney.
- Return Prepaid postcard.

CLAIMS AS FILED

FOR	NUMBER FILED	NUMBER EXTRA	RATE	FEE
Basic Fee			\$740.00	\$740.00
Total Claims	11	— 20 = 0	× \$18.00	\$0.00
Independent Claims	3	— 3 = 0	× \$84.00	\$0.00
If application contains any multiple dependent claim(s), then add			\$280.00	\$0.00
TOTAL FILING FEE				\$740.00

- A check in the amount of \$740.00 cover the filing fee is enclosed.
- A check in the amount of \$40.00 to cover the assignment recording fee.
- A duplicate copy of this sheet is enclosed.



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CERTIFICATE OF MAILING BY "EXPRESS MAIL"

Docket No. : **JCLA7022**
Applicant(s) : **Ko-Yan Shih; Ming-Hsun Hsu**
For : **METHOD AND CIRCUIT FOR TESTING A CHIP**
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Mailing Label No.
Date of Deposit : *October 22, 2001*

I hereby certify that the accompanying

Transmittal in Duplicate; Specification 14 pages, 4 sheets of drawings; **SIGNED**
Declaration and Power of Attorney 2 pages; Recordation Form Cover Sheet and
Assignment 3 pages; Checks for Filing Fee(s); Return Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

M. Chang
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